



**Re: 1907/2006/EC REACH Position Statement**

To Whom It May Concern:

Regulation 1907/2006/EC – the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH) addresses substances on their own, in preparations, or as substances in articles. Analog Devices, Inc.'s (ADI) products are classified under REACH as articles with substances not intended for release. ADI has evaluated its component products and shipping materials, and determined, except as noted in Appendix 1, that none contain any of the two hundred nine (209) currently identified substances of very high concern (SVHC) in excess of the 0.1% (by weight) threshold as published on June 25, 2020. Moreover, ADI has evaluated its component products and shipping materials, and has determined that none contain any of the restricted substances stated in the current version of Annex XVII defined in Article 67 of the REACH Directive.

ADI will continue to monitor any amendments to 1907/2006/EC and will perform its reasonable due diligence by obtaining necessary evidences from its supply chain regarding compliance of its component products and shipping materials.

The information on ADI products in this letter is based upon information provided by the material suppliers and assembly manufacturers used by ADI to manufacture these products. As such, ADI makes no independent representations or warranties, expressed or implied, and assumes no liability in connection with the use of this information.

Thank you for your interest in ADI products.

A handwritten signature in black ink, appearing to read "Susan Capuli", written over a horizontal line.

Susan Capuli  
Director of Environmental, Health & Safety

## Appendix 1

Substance Name	CAS number	EC number	ECHA Candidate List Date	Impacted Products
Lead	7439-92-1	231-100-4	June 27, 2018	ADI Products identified as RoHS Exempt or Non-RoHS Compliant contain lead at >0.1 wt% in article
Bisphenol-A	80-05-7	201-245-8	January 12, 2017	ADI Laminated Products identified as non-halogen free contain bisphenol-A (BPA) at >0.1 wt% in article
Nonylphenol			June 20, 2013	Die attach material used in ADI hermetic products may contain Nonyl Phenol >0.1 wt% in article
Hexahydromethylphthalic anhydride	25550-51-0	247-094-1	December 19, 2012	Epoxy underfill material used in ADI Module product may contain Hexahydromethylphthalic anhydride >0.1 wt% in article